

Company Profile

General

- Eltek provides the High Tech industry with innovative solutions based on the commitment to Rigid and Flex-Rigid advanced technology and proactive customer care.
- Eltek was incorporated in 1970. Since 1997, Eltek has been publicly traded on the NASDAQ (Symbol: ELTK). Kubatronik Leiterplatten GmbH – Eltek’s European manufacturing subsidiary specializes in small volume, quick turnaround products.
- Since 2013 Eltek is part of the Nistec Group, one of the largest EMS in Israel. Nistec specializes in Design and Assembly of printed circuit boards, small and medium volumes.

Strategy

- Adding engineering value early in the design cycle.
- Providing innovative, cost effective and reliable solutions.
- Enabling the technology edge, when needed while increasing reliability and durability.
- Enabling innovative technologies.
- **HATS and IST proven reliability.**

The Eltek Way to Success

- Focus on value added engineering methods.
- Search for and use advanced base material.
- Continuously invest in state of the art equipment and manufacturing techniques.
- Implement state of the art technologies as a derivative of the market requirements.
- Share with you our accumulated engineering knowledge.
- Become your vendor of choice.

Ready to Welcome a Challenge

Intensive investment in R&D, trained personnel and production expertise, allows Eltek to provide high performance products incorporating the most advanced materials and technologies.

Eltek maintains its exceptionally high standards through an equal emphasis on processes, technology and human resources.

Our employees know that sharing our competencies with our customers will enable them to meet their objectives.

Qualifications

- AS9100C
- ISO 9001:2008
- ISO 14001:2004
- OHSAS 18001:2007
- MIL-PRF-55110G
- MIL-P-50884E
- UL 94V-0
- **Nadcap**
- Adheres to all relevant IPC standards



Eltek Highlights

Flex-Rigid

- 75/75 micron (3/3 MILS) Line / Space - Ultra High
- Density. Complex construction up to 30 layers.
- Sequential build-up with Microvias, blind and
- buried Vias. Special Flex -Rigid construction for
- dynamic applications. Bookbinder build-up.
- Flexible silver ink shielding.

Thermal Dissipation & CTE Solutions

- Internal and external Heat
- Sinks. 3D Heat Sinks.
Heavy copper inner
- layers. Built in Ceramic
- substrate. Low CTE
- materials.

HDI Technology

- Staggered and stacked Microvias.
- Sequential build up to: 4+N+4.
- Blind and buried Vias.
- Via filling: Via in pad, Microvia fill.

RF & Microwave

- Full PTFE multilayer construction.
- Mixed PTFE / FR4 / Polyimide, Rigid and Flex-Rigid build up.
- High precision line width, geometry and tolerance.
- RF compatible surface finishes.
- Materials: Rogers, Arlon, Taconic.

Forthcoming Technologies

- Embedded components.
- EUT - Eltek Ultra-thin boards.

For more detailed information, please look at our website.

